



#### ZXM66P02N8



# 20V P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	ID
-20V	0.025Ω	-8.0A

# **Description and Applications**

This high density MOSFET utilizes a unique structure that combines the benefits of a low on-resistance with fast switching speed. This makes it ideal for high efficiency, low voltage power management applications. Compared to trenchFET technology, this MOSFET structure has an intrinsically higher pulse current handling capability in linear mode.

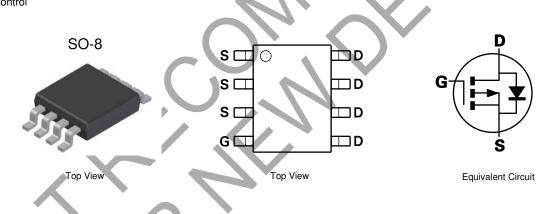
- Inrush protection circuits
- DC-DC Converters
- Power management functions
- Disconnect switches
- Motor control

## **Features and Benefits**

- High pulse current handling in linear mode
- Low on-resistance
- Fast switching speed
- Low gate drive
- Low profile SOIC package

# **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)

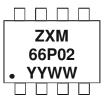


### Ordering Information (Note 1)

Product	roduct Marking		Reel size (inches)	Tape width (mm)	Quantity per reel					
ZXM66P02N8TA		See below	7	12	500					

Notes: 1. For packaging details, go to our website.

## **Marking Information**



ZXM = Product Type Marking Code, Line 1 66P02 = Product Type Marking Code, Line 2 YYWW = Date Code Marking YY = Year (ex: 09 = 2009) WW = Week (01-52) Notes:

#### Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic Drain-Source voltage Gate-Source voltage			Symbol	Value	Unit V V	
			V <sub>DSS</sub>	-20		
			V <sub>GS</sub>	±12		
		(Note 3)		-8.0		
Continuous Drain current	$V_{GS} = 4.5V$	$T_{A} = 70^{\circ}C$ (Note 3)	ID	-6.5	А	
		(Note 2)		-6.4		
Pulsed Drain current (Note 4)		(Note 4)	I <sub>DM</sub>	-28	А	
Continuous Source current (Body diode) (Note 3		(Note 3)	ls	-4.15	А	
Pulsed Source current (Body diode) (Note 4)		I <sub>SM</sub>	-28	A		
	<u>,</u>		000		9	

## Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Power dissipation Linear derating factor	(Note 2)		1.56 12.5	w
	(Note 3)	PD	mW/°C	
Thermal Resistance, Junction to Ambient	(Note 2) (Note 3)	R <sub>0</sub> JA	80 50	°C/W
Operating and storage temperature range	· · ·	TJ, T <sub>STG</sub>	-55 to 150	°C

2. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.

3. Same as note (3), except the device is measured at t  $\leq$  10 sec.

4. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.05, pulse width 10 µs - pulse width limited by maximum junction temperature.

# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

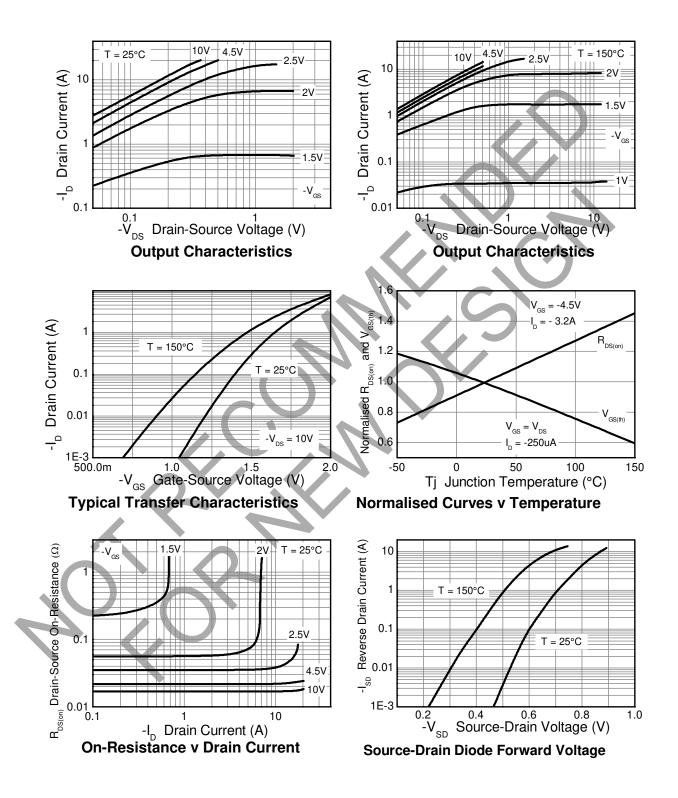
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	—		V	$I_D=-250\mu A,\ V_{GS}=0V$		
Zero Gate Voltage Drain Current	IDSS			-1	μA	$V_{DS}=-16V,\ V_{GS}=0V$		
Gate-Source Leakage	I <sub>GSS</sub>			-100	nA	$V_{GS}=\pm 12V, \ V_{DS}=0V$		
ON CHARACTERISTICS								
Gate Threshold Voltage	V <sub>GS</sub> (th)	-0.7			V	$I_D = -250 \mu A, \ V_{DS} = V_{GS}$		
Static Drain-Source On-Resistance (Note 5)				0.025	Ω	$V_{GS} = -4.5V, I_D = -3.2A$		
Static Drain-Source On-Resistance (Note 5)	R <sub>DS</sub> (ON)		_	0.045	12	$V_{GS} = -2.5V, I_D = -2.7A$		
Forward Transconductance (Notes 5 & 6)	<b>g</b> fs	_	13.3	_	S	$V_{DS} = -10V, I_D = -3.2A$		
Diode Forward Voltage (Note 5)	V <sub>SD</sub>	_	_	0.95	V	$I_S = -3.2A, V_{GS} = 0V$		
Reverse recovery time (Note 6)	t <sub>rr</sub>		23.1 —	ns				
Reverse recovery charge (Note 6)	Q <sub>rr</sub>	_	12.2		nC	- I <sub>F</sub> = -3.2A, di/dt = 100A/μs		
DYNAMIC CHARACTERISTICS (Note 6)								
Input Capacitance	Ciss	_	2068		pF			
Output Capacitance	Coss	_	1038		pF	− V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V − F = 1MHz		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	506		pF			
Total Gate Charge (Note 7)	Qg	_	43.3		nC	N/ 15/1/1 10/1		
Gate-Source Charge (Note 7)	Q <sub>gs</sub>	_	3.5		nC	−V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -10V, −I <sub>D</sub> = -3.2A		
Gate-Drain Charge (Note 7)	Q <sub>gd</sub>	_	21.3		nC	10 = -3.2A		
Turn-On Delay Time (Note 7)	t <sub>D(on)</sub>	_	14.0		ns			
Turn-On Rise Time (Note 7)	t <sub>r</sub>	_	44.3		ns	V <sub>DD</sub> = -10V, V <sub>GS</sub> = -5V		
Turn-Off Delay Time (Note 7)	t <sub>D(off)</sub>	_	118.4		ns	$I_D = -3.2A, R_G = 6.0\Omega$		
Turn-Off Fall Time (Note 7)	t <sub>f</sub>	_	98.4		ns	7		

5. Measured under pulsed conditions. Pulse width  $\leq 300 \mu s;$  duty cycle  $\leq 2\%$ 

For design aid only, not subject to production testing.
 Switching characteristics are independent of operating junction temperatures.

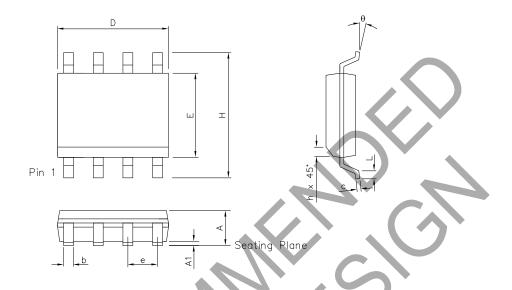
Notes:





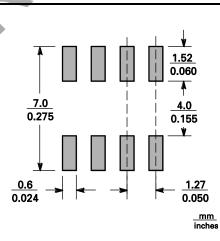


# **Package Outline Dimensions**



DIM	Inc	Inches		Millimeters		Inches		Millimeters		
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.	
А	0.053	0.069	1.35	1.75	е	0.050	050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013	0.020	0.33	0.51	
D	0.189	0.197	4.80	5.00	c	0.008	0.010	0.19	0.25	
н	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°	
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50	
L	0.016	0.050	0.40	1.27	-	-	-	-	-	

# Suggested Pad Layout





#### IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2009, Diodes Incorporated

#### www.diodes.com